

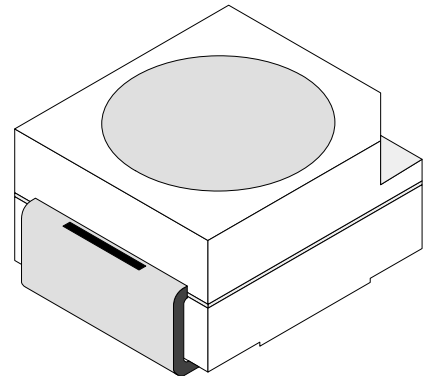
## GaAIAs/GaAIAs Infrared Emitting Diode in SMT Package

### Description

TSMF3700 is a high speed infrared emitting diode in GaAIAs on GaAIAs double hetero (DH) technology in a miniature PL-CC-2 SMD package.

It has been designed to meet the increasing demand on optoelectronic devices for surface mounting.

The package consists of a lead frame which is surrounded with a white thermoplast. The reflector inside the package is filled up with clear epoxy.



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### Features

- SMT IRED with extra high radiant power
- Low forward voltage
- Compatible with automatic placement equipment
- EIA and ICE standard package
- Suitable for infrared, vapor phase and wave-solder process
- Available in 8 mm tape
- Suitable for pulse current operation
- Extra wide angle of half intensity  $\varphi = \pm 60^\circ$
- Peak wavelength  $\lambda_p = 870 \text{ nm}$
- High reliability

### Applications

Infrared source in tactile keyboards

IR diode in low space applications

High performance PCB mounted infrared sensors

High power infrared emitter for miniature light barriers

### Absolute Maximum Ratings

$T_{amb} = 25^{\circ}\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		$V_R$	5	V
Forward Current		$I_F$	100	mA
Peak Forward Current	$t_p/T = 0.5, t_p = 100 \mu\text{s}$	$I_{FM}$	200	mA
Surge Forward Current	$t_p = 100 \mu\text{s}$	$I_{FSM}$	1	A
Power Dissipation		$P_V$	160	mW
Junction Temperature		$T_j$	100	$^{\circ}\text{C}$
Operating Temperature Range		$T_{amb}$	-55...+100	$^{\circ}\text{C}$
Storage Temperature Range		$T_{stg}$	-55...+100	$^{\circ}\text{C}$
Soldering Temperature	$t \leq 10\text{sec}$	$T_{sd}$	260	$^{\circ}\text{C}$
Thermal Resistance Junction/Ambient		$R_{thJA}$	450	K/W

### Basic Characteristics

$T_{amb} = 25^{\circ}\text{C}$

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	$V_F$		1.4	1.7	V
	$I_F = 1 \text{ A}, t_p = 100 \mu\text{s}$	$V_F$		2.4		V
Temp. Coefficient of $V_F$	$I_F = 100\text{mA}$	$TK_{V_F}$		-1.7		mV/K
Reverse Current	$V_R = 5 \text{ V}$	$I_R$			10	$\mu\text{A}$
Junction Capacitance	$V_R = 0 \text{ V}, f = 1 \text{ MHz}, E = 0$	$C_j$		160		pF
Radiant Intensity	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	$I_e$		7		mW/sr
	$I_F = 1 \text{ A}, t_p = 100 \mu\text{s}$	$I_e$		60		mW/sr
Radiant Power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	$\phi_e$		32		mW
Temp. Coefficient of $\phi_e$	$I_F = 100 \text{ mA}$	$TK_{\phi_e}$		-0.8		%/K
Angle of Half Intensity		$\phi$		$\pm 60$		deg
Peak Wavelength	$I_F = 100 \text{ mA}$	$\lambda_p$		870		nm
Spectral Bandwidth	$I_F = 100 \text{ mA}$	$\Delta\lambda$		40		nm
Temp. Coefficient of $\lambda_p$	$I_F = 100 \text{ mA}$	$TK_{\lambda_p}$		0.2		nm/K
Rise Time	$I_F = 100 \text{ mA}$	$t_r$		30		ns
Fall Time	$I_F = 100 \text{ mA}$	$t_f$		30		ns

## Typical Characteristics ( $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified)

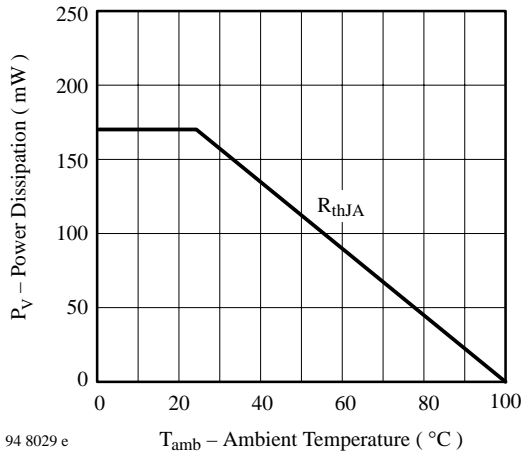


Figure 1. Power Dissipation vs. Ambient Temperature

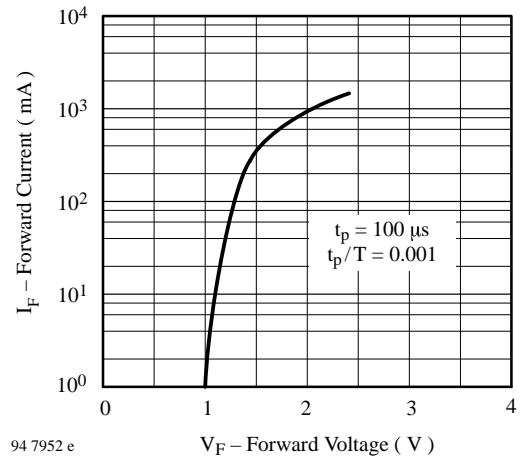


Figure 4. Forward Current vs. Forward Voltage

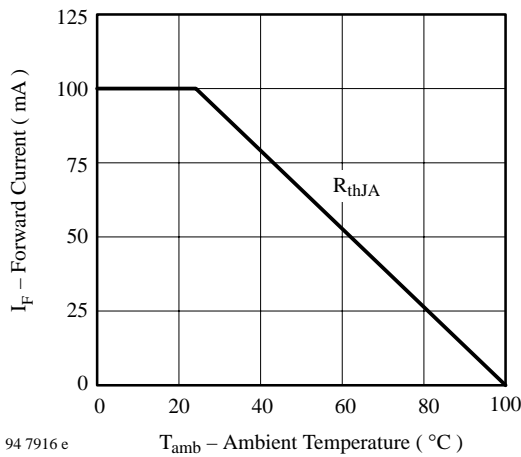


Figure 2. Forward Current vs. Ambient Temperature

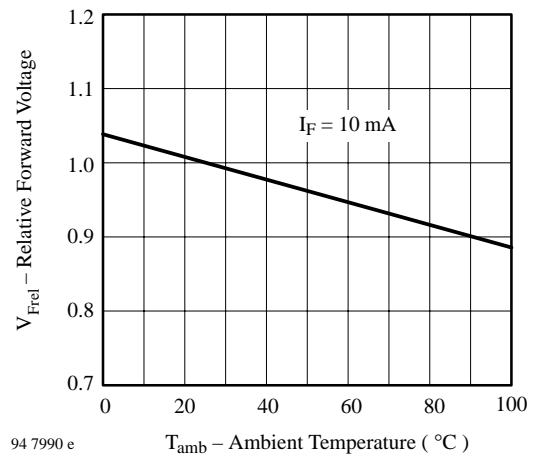


Figure 5. Relative Forward Voltage vs. Ambient Temperature

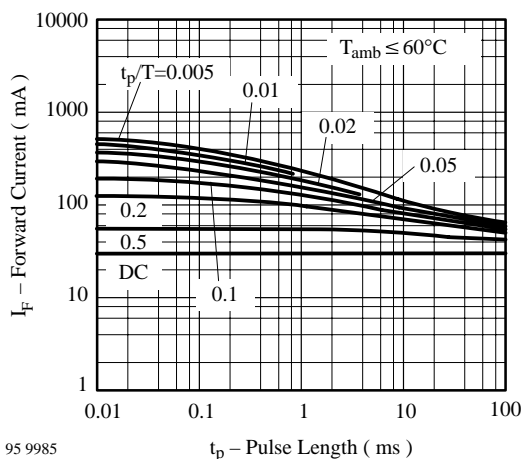


Figure 3. Pulse Forward Current vs. Pulse Duration

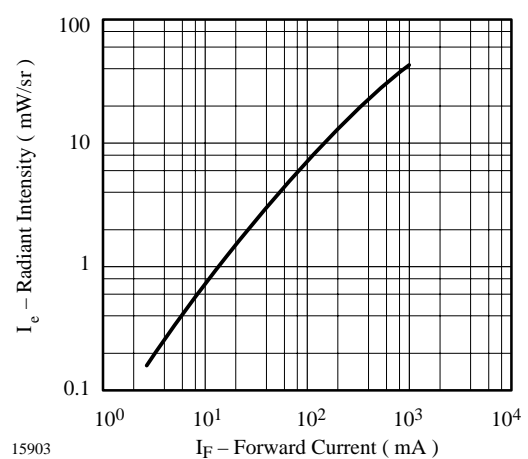


Figure 6. Radiant Intensity vs. Forward Current

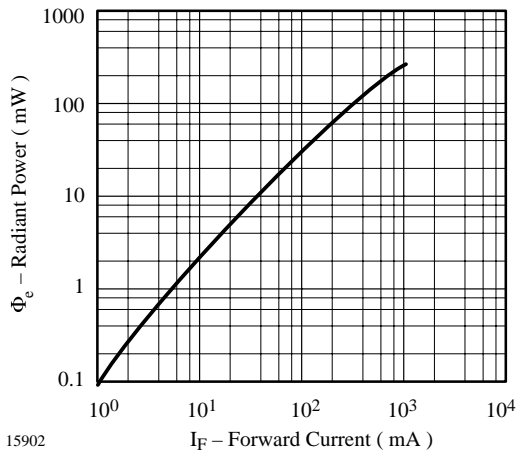


Figure 7. Radiant Power vs. Forward Current

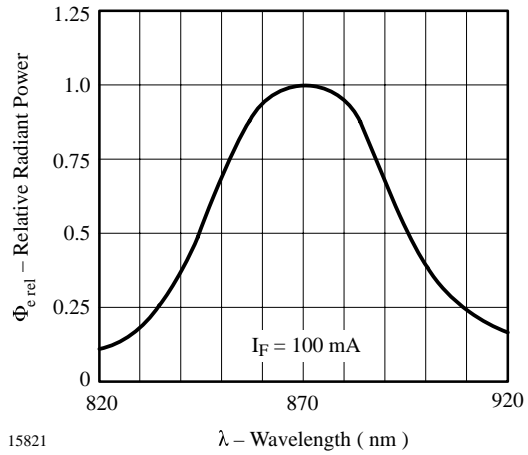


Figure 9. Relative Radiant Power vs. Wavelength

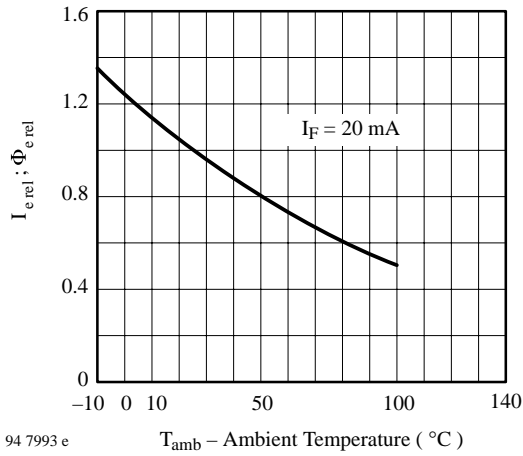


Figure 8. Rel. Radiant Intensity/Power vs. Ambient Temperature

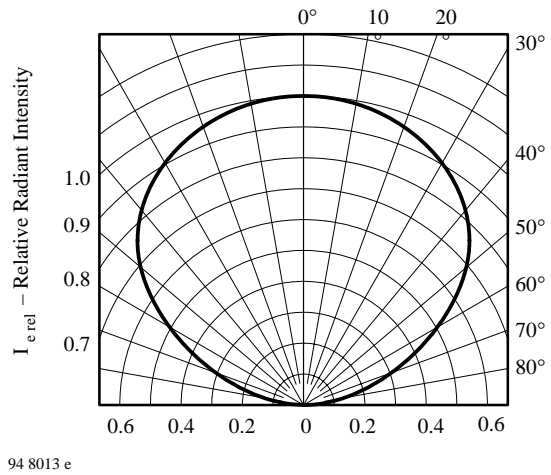
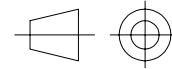
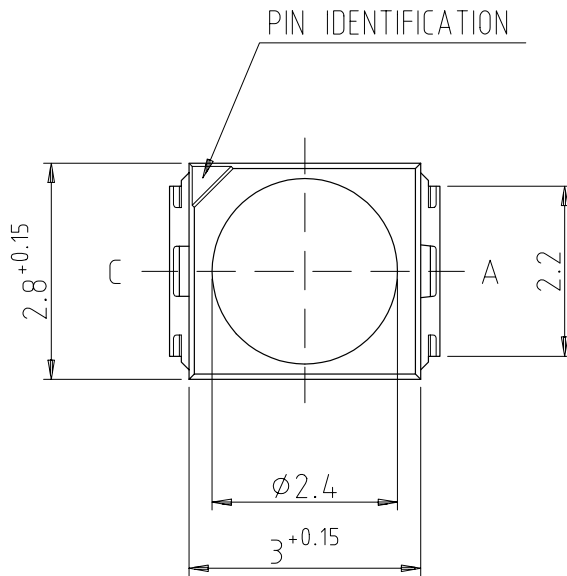
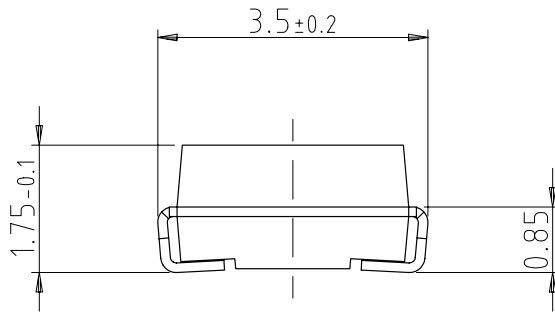


Figure 10. Relative Radiant Intensity vs. Angular Displacement

**Dimensions in mm**



technical drawings  
according to DIN  
specifications

95 11314

### Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**Vishay Semiconductor GmbH** has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**Vishay Semiconductor GmbH** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

**We reserve the right to make changes to improve technical design and may do so without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay-Telefunken products for any unintended or unauthorized application, the buyer shall indemnify Vishay-Telefunken against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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